

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Jeffrey L. Deeney

Confirmation No.: 5995

Application No.: 09/992,864

Examiner: Hung S. Bui

Filing Date: 11/16/01

Group Art Unit: 2841

Title: METHOD AND APPARATUS FOR SUPPORTING CIRCUIT COMPONENT HAVING
SOLDER COLUMN ARRAY INTERCONNECTS USING INTERPOSED SUPPORT SHIMS

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- (X) Response/Amendment () Petition to extend time to respond
() New fee as calculated below () Supplemental Declaration
() No additional fee (Address envelope to "Mail Stop Non-Fee Amendment")
() Other: Return Postcard. (fee \$)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS		MINUS		= 0	X \$18	\$ 0
INDEP. CLAIMS		MINUS		= 0	X \$86	\$ 0
[] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$290	\$ 0
EXTENSION FEE	1ST MONTH \$110.00	2ND MONTH \$420.00	3RD MONTH \$950.00	4TH MONTH \$1480.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

"Express Mail" label no. EV406076670US

Date of Deposit 4/26/04

I hereby certify that this is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Commissioner for Patents, Alexandria, VA 22313-1450.

By Jennifer Yap

Typed Name: Jennifer Yap

Respectfully submitted,

Jeffrey L. Deeney

By Roland A. Fuller III

Roland A. Fuller III

Attorney/Agent for Applicant(s)

Reg. No. 31,160

EV 406 076 670 US Date: 4/26/04



PATENT

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Applicant: Jeffrey L. Deeney
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Title: METHOD AND APPARATUS FOR SUPPORTING
CIRCUIT COMPONENT HAVING SOLDER COLUMN
ARRAY INTERCONNECTS USING INTERPOSED
SUPPORT SHIMS
Attorney Docket: 10015588-1

Director of The United States Patent and Trademark Office
P.O. Box 1450
Alexandria, Virginia 22313-1450

RESPONSE

Sir:

In response to the Office Action mailed February 19, 2004, please consider the remarks set forth below.

A listing of the Claims begins on page 2 of this paper.

Remarks begin on page 7 of this paper.